

## 50 mA, 100 mA, 150 mA CMOS LDOs with Shutdown and Reference Bypass

### Features

- AEC-Q100 Automotive Qualified, See [Product Identification System](#)
- Low Supply Current: 80  $\mu\text{A}$  (Max)
- Low Dropout Voltage: 140 mV (Typ.) @ 150 mA
- High-Output Voltage Accuracy:  $\pm 0.4\%$  (Typ.)
- Standard or Custom Output Voltages
- Power-Saving Shutdown Mode
- Reference Bypass Input for Ultra Low-Noise Operation
- Fast Shutdown Response Time: 60  $\mu\text{sec}$  (Typ.)
- Overcurrent and Overtemperature Protection
- Space-Saving 5-Pin SOT-23A Package
- Pin-Compatible Upgrades for Bipolar Regulators
- Wide Operating Temperature Range:  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$
- Standard Output Voltage Options:
  - 1.8V, 2.5V, 2.6V, 2.7V, 2.8V, 2.85V, 3.0V, 3.3V, 5.0V

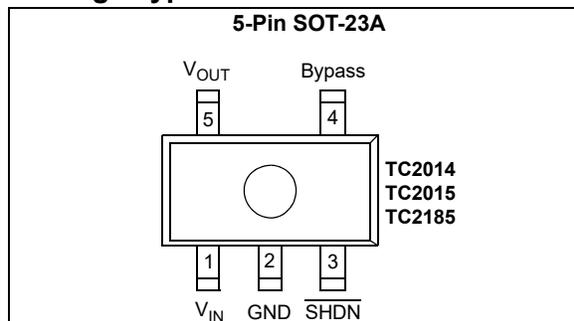
### Applications

- Battery-Operated Systems
- Portable Computers
- Medical Instruments
- Instrumentation
- Cellular/GSM/PHS Phones
- Linear Post-Regulator for SMPS
- Pagers

### Related Literature

- Application Notes: AN765, AN766, AN776 and AN792

### Package Type



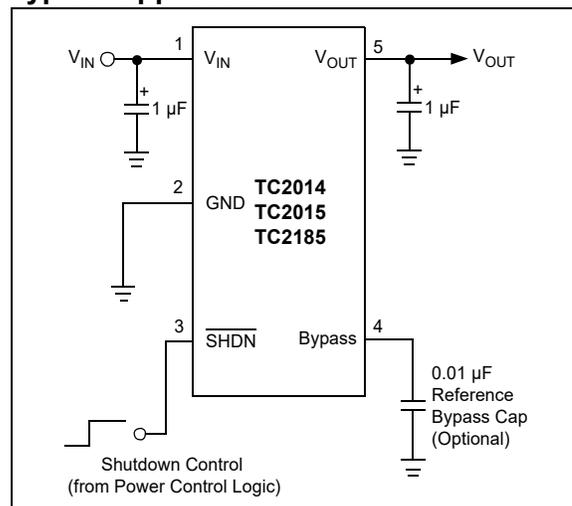
### General Description

The TC2014, TC2015 and TC2185 are high-accuracy (typically  $\pm 0.4\%$ ) CMOS upgrades for bipolar Low Drop-out Regulators (LDOs), such as the LP2980. Total supply current is typically 55  $\mu\text{A}$ ; 20 to 60 times lower than in bipolar regulators.

The key features of the device include low noise operation (plus bypass reference), low dropout voltage – typically 45 mV for the TC2014, 90 mV for the TC2015, and 140 mV for the TC2185, at full load – and fast response to step changes in load. Supply current is reduced to 0.5  $\mu\text{A}$  (max) and  $V_{OUT}$  falls to zero when the shutdown input is low. These devices also incorporate overcurrent and overtemperature protection.

The TC2014, TC2015 and TC2185 are stable with an output capacitor of 1  $\mu\text{F}$  and have maximum output currents of 50 mA, 100 mA and 150 mA, respectively. For higher-output current versions, see the TC1107 (DS20001356), TC1108 (DS20001357) and TC1173 (DS20001362) ( $I_{OUT} = 300\text{ mA}$ ) data sheets.

### Typical Application



# TC2014/2015/2185

## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings†

Input Voltage .....	7.0V
Output Voltage .....	(-0.3) to (V <sub>IN</sub> + 0.3)
Operating Temperature .....	-40°C < T <sub>J</sub> < 125°C
Storage Temperature.....	-65°C to +150°C
Maximum Voltage on Any Pin.....	V <sub>IN</sub> + 0.3V to -0.3V
Maximum Junction Temperature .....	150°C
ESD Protection on all pins <sup>(1)</sup> :	
HBM .....	±4000V
MM .....	±200V
CDM .....	±1500V

† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

**Note 1:** Testing was performed per AEC-Q100 Standards. ESD CDM was tested on the 5L SOT-23 package. For additional information please contact your local Microchip sales office.

## ELECTRICAL CHARACTERISTICS

**Electrical Specifications:** Unless otherwise specified, V<sub>IN</sub> = V<sub>R</sub> + 1V, I<sub>L</sub> = 100 μA, C<sub>OUT</sub> = 3.3 μF, SHDN > V<sub>IH</sub>, T<sub>A</sub> = +25°C. **BOLDFACE** type specifications apply for junction temperature of -40°C to +125°C.

Parameters	Sym	Min	Typ	Max	Units	Conditions
Input Operating Voltage	V <sub>IN</sub>	<b>2.7</b>	—	<b>6.0</b>	V	<a href="#">Note 1</a>
Maximum Output Current	I <sub>OUTMAX</sub>	<b>50</b>	—	—	mA	<b>TC2014</b>
		<b>100</b>	—	—		<b>TC2015</b>
		<b>150</b>	—	—		<b>TC2185</b>
Output Voltage	V <sub>OUT</sub>	<b>V<sub>R</sub> - 2.0%</b>	V <sub>R</sub> ± 0.4%	<b>V<sub>R</sub> + 2.0%</b>	V	<a href="#">Note 2</a>
V <sub>OUT</sub> Temperature Coefficient	TCV <sub>OUT</sub>	—	20	—	ppm/°C	<a href="#">Note 3</a>
		—	<b>40</b>	—		
Line Regulation	ΔV <sub>OUT</sub> /ΔV <sub>IN</sub>	—	0.05	<b>0.5</b>	%	(V <sub>R</sub> + 1V) ≤ V <sub>IN</sub> ≤ 6V
Load Regulation <a href="#">(Note 4)</a>	ΔV <sub>OUT</sub> /V <sub>OUT</sub>	<b>-1.0</b>	0.33	<b>+1.0</b>	%	<b>TC2014;TC2015:</b> I <sub>L</sub> = 0.1 mA to I <sub>OUTMAX</sub>
		<b>-2.0</b>	0.43	<b>+2.0</b>		<b>TC2185:</b> I <sub>L</sub> = 0.1 mA to I <sub>OUTMAX</sub> <a href="#">(Note 4)</a>

- Note 1:** The minimum V<sub>IN</sub> has to meet two conditions: V<sub>IN</sub> = 2.7V and V<sub>IN</sub> = V<sub>R</sub> + V<sub>DROPOUT</sub>.  
**2:** V<sub>R</sub> is the regulator output voltage setting. For example: V<sub>R</sub> = 1.8V, 2.7V, 2.8V, 2.85V, 3.0V, 3.3V.  
**3:**

$$TCV_{OUT} = \frac{(V_{OUTMAX} - V_{OUTMIN}) \times 10^{-6}}{V_{OUT} \times \Delta T}$$

- 4:** Regulation is measured at a constant junction temperature using low duty cycle pulse testing. Load regulation is tested over a load range from 1.0 mA to the maximum specified output current. Changes in output voltage due to heating effects are covered by the Thermal Regulation specification.  
**5:** Dropout Voltage is defined as the input-to-output differential at which the output voltage drops 2% below its nominal value.  
**6:** Thermal Regulation is defined as the change in output voltage at a time T after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a current pulse equal to I<sub>MAX</sub> at V<sub>IN</sub> = 6V for T = 10 ms.  
**7:** The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction-to-air (i.e. T<sub>A</sub>, T<sub>J</sub>, θ<sub>JA</sub>).  
**8:** Time required for V<sub>OUT</sub> to reach 95% of V<sub>R</sub> (output voltage setting), after V<sub>SHDN</sub> is switched from 0 to V<sub>IN</sub>.

## ELECTRICAL CHARACTERISTICS (CONTINUED)

<b>Electrical Specifications:</b> Unless otherwise specified, $V_{IN} = V_R + 1V$ , $I_L = 100 \mu A$ , $C_{OUT} = 3.3 \mu F$ , $\overline{SHDN} > V_{IH}$ , $T_A = +25^\circ C$ . <b>BOLDFACE</b> type specifications apply for junction temperature of $-40^\circ C$ to $+125^\circ C$ .						
Parameters	Sym	Min	Typ	Max	Units	Conditions
Dropout Voltage	$V_{IN} - V_{OUT}$	—	2	—	mV	<b>(Note 5)</b> $I_L = 100 \mu A$
		—	45	<b>70</b>		$I_L = 50 mA$
		—	90	<b>140</b>		<b>TC2015; TC2185</b> $I_L = 100 mA$
		—	140	<b>210</b>		<b>TC2185</b> $I_L = 150 mA$
Supply Current	$I_{IN}$	—	55	<b>80</b>	$\mu A$	$\overline{SHDN} = V_{IH}$ , $I_L = 0$
Shutdown Supply Current	$I_{INSD}$	—	0.05	0.5	$\mu A$	$\overline{SHDN} = 0V$
Power Supply Rejection Ratio	PSRR	—	55	—	dB	$F \leq 1 kHz$ , $C_{bypass} = 0.01 \mu F$
Output Short Circuit Current	$I_{OUTSC}$	—	160	300	mA	$V_{OUT} = 0V$
Thermal Regulation	$\Delta V_{OUT}/\Delta P_D$	—	0.04	—	V/W	<b>Note 6, Note 7</b>
Thermal Shutdown Die Temperature	$T_{SD}$	—	160	—	$^\circ C$	
Output Noise	eN	—	200	—	nV/ $\sqrt{Hz}$	$I_L = I_{OUTMAX}$ , $F = 10 kHz$ 470 pF from Bypass to GND
Response Time (from Shutdown Mode) <b>(Note 8)</b>	$T_R$	—	60	—	$\mu s$	$V_{IN} = 4V$ , $I_L = 30 mA$ , $C_{IN} = 1 \mu F$ , $C_{OUT} = 10 \mu F$
<b>SHDN Input</b>						
SHDN Input High Threshold	$V_{IH}$	<b>60</b>	—	—	% $V_{IN}$	$V_{IN} = 2.5V$ to $6.0V$
SHDN Input Low Threshold	$V_{IL}$	—	—	<b>15</b>	% $V_{IN}$	$V_{IN} = 2.5V$ to $6.0V$

- Note 1:** The minimum  $V_{IN}$  has to meet two conditions:  $V_{IN} = 2.7V$  and  $V_{IN} = V_R + V_{DROPOUT}$ .  
**Note 2:**  $V_R$  is the regulator output voltage setting. For example:  $V_R = 1.8V, 2.7V, 2.8V, 2.85V, 3.0V, 3.3V$ .  
**Note 3:**

$$TCV_{OUT} = \frac{(V_{OUTMAX} - V_{OUTMIN}) \times 10^{-6}}{V_{OUT} \times \Delta T}$$

- Note 4:** Regulation is measured at a constant junction temperature using low duty cycle pulse testing. Load regulation is tested over a load range from 1.0 mA to the maximum specified output current. Changes in output voltage due to heating effects are covered by the Thermal Regulation specification.  
**Note 5:** Dropout Voltage is defined as the input-to-output differential at which the output voltage drops 2% below its nominal value.  
**Note 6:** Thermal Regulation is defined as the change in output voltage at a time T after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a current pulse equal to  $I_{MAX}$  at  $V_{IN} = 6V$  for  $T = 10 ms$ .  
**Note 7:** The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction-to-air (i.e.  $T_A$ ,  $T_J$ ,  $\theta_{JA}$ ).  
**Note 8:** Time required for  $V_{OUT}$  to reach 95% of  $V_R$  (output voltage setting), after  $\overline{V_{SHDN}}$  is switched from 0 to  $V_{IN}$ .

# TC2014/2015/2185

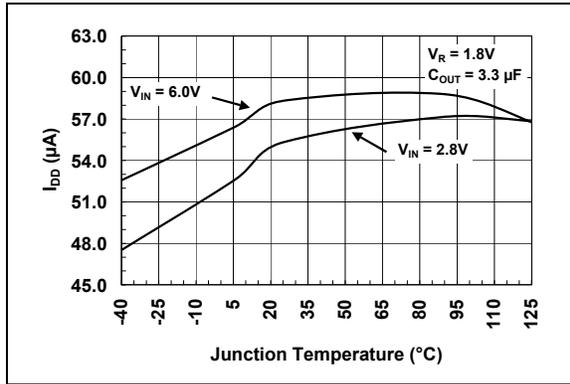
## TEMPERATURE CHARACTERISTICS

<b>Electrical Specifications:</b> Unless otherwise noted, $V_{DD} = +2.7V$ to $+6.0V$ and $V_{SS} = GND$ .						
Parameters	Sym	Min	Typ	Max	Units	Conditions
<b>Temperature Ranges:</b>						
Extended Temperature Range	$T_A$	-40	—	+125	°C	
Operating Temperature Range	$T_A$	-40	—	+125	°C	
Storage Temperature Range	$T_A$	-65	—	+150	°C	
<b>Thermal Package Resistances:</b>						
Thermal Resistance, 5L-SOT-23	$\theta_{JA}$	—	255	—	°C/W	

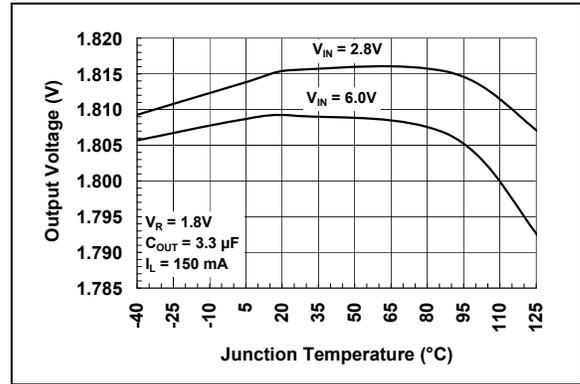
## 2.0 TYPICAL PERFORMANCE CURVES

**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

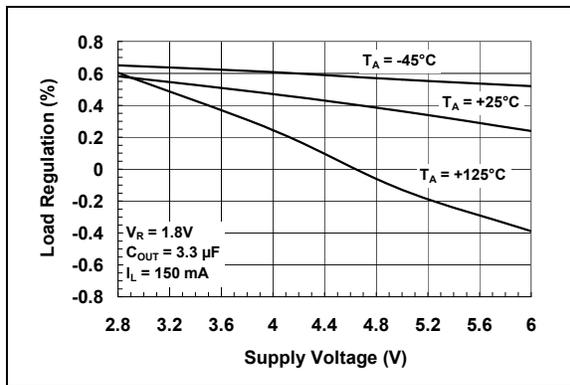
**Note:** Unless otherwise indicated,  $V_{IN} = V_R + 1V$ ,  $I_L = 100 \mu A$ ,  $C_{OUT} = 3.3 \mu F$ ,  $SHDN > V_{IH}$ ,  $T_A = +25^\circ C$ .



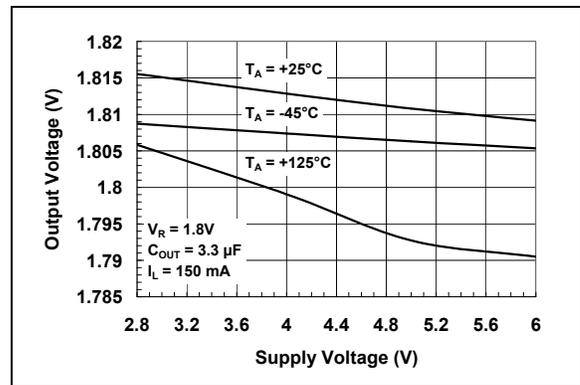
**FIGURE 2-1:** Supply Current vs. Junction Temperature.



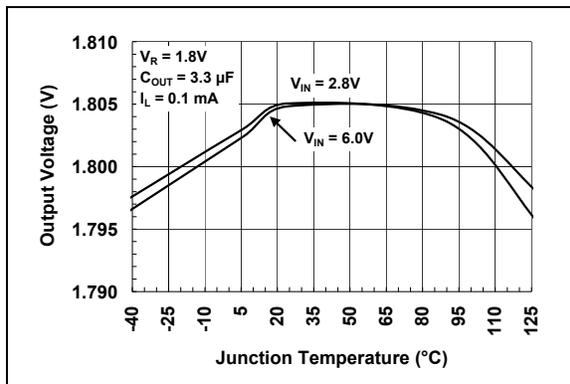
**FIGURE 2-4:** Output Voltage vs. Junction Temperature.



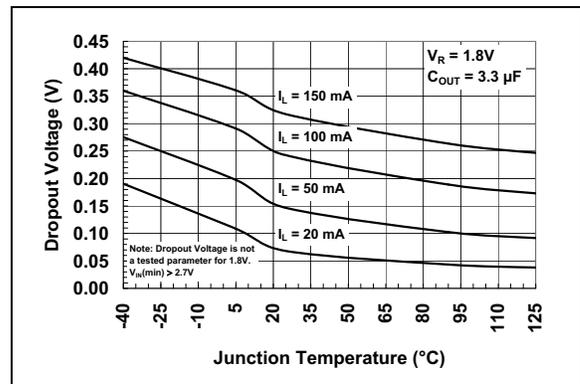
**FIGURE 2-2:** Load Regulation vs. Supply Voltage.



**FIGURE 2-5:** Output Voltage vs. Supply Voltage.



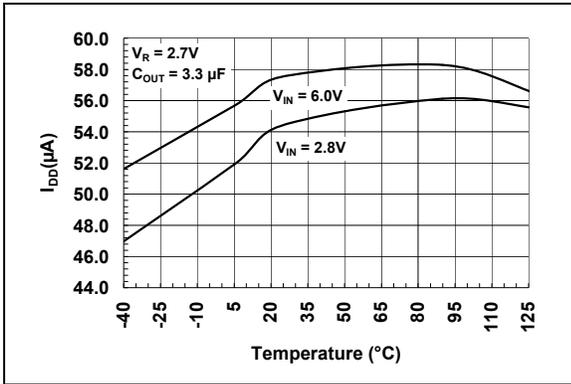
**FIGURE 2-3:** Output Voltage vs. Junction Temperature.



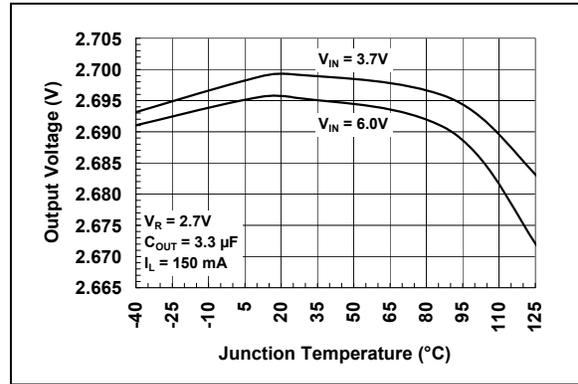
**FIGURE 2-6:** Dropout Voltage vs. Junction Temperature.

# TC2014/2015/2185

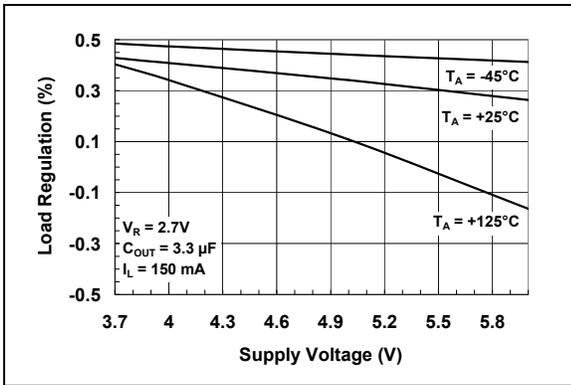
Note: Unless otherwise indicated,  $V_{IN} = V_R + 1V$ ,  $I_L = 100 \mu A$ ,  $C_{OUT} = 3.3 \mu F$ ,  $\overline{SHDN} > V_{IH}$ ,  $T_A = +25^\circ C$ .



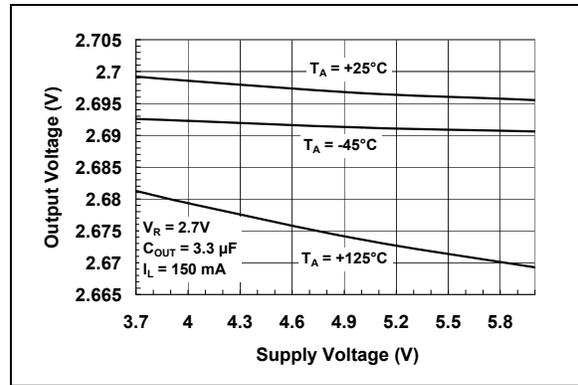
**FIGURE 2-7:** Supply Current vs. Junction Temperature.



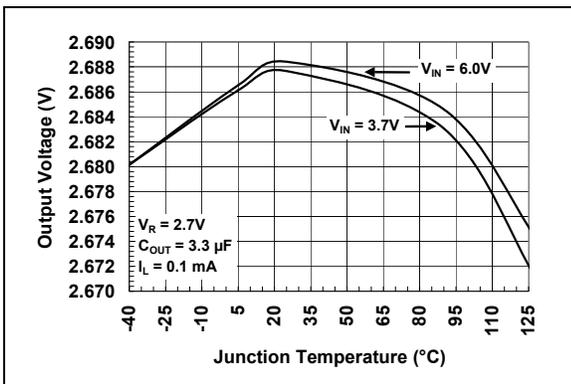
**FIGURE 2-10:** Output Voltage vs. Junction Temperature.



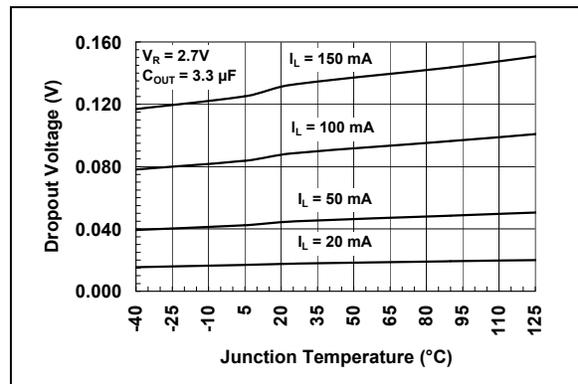
**FIGURE 2-8:** Load Regulation vs. Supply Voltage.



**FIGURE 2-11:** Output Voltage vs. Supply Voltage.

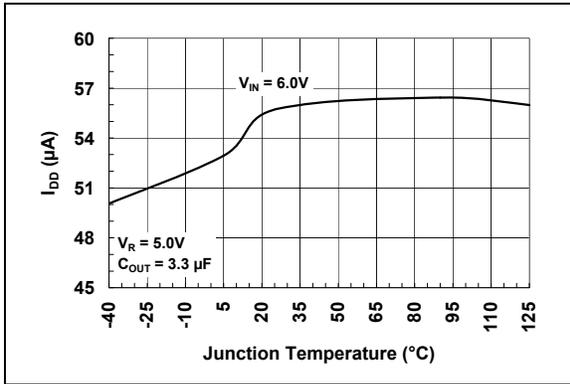


**FIGURE 2-9:** Output Voltage vs. Junction Temperature.

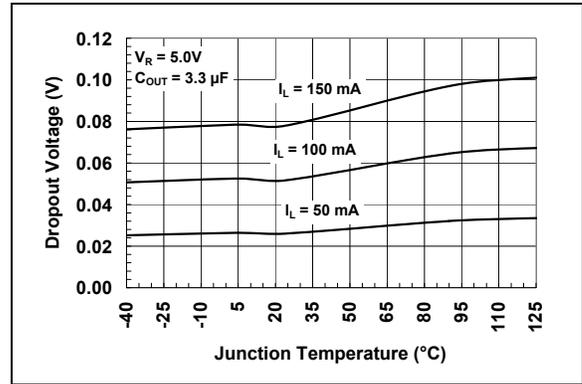


**FIGURE 2-12:** Dropout Voltage vs. Junction Temperature.

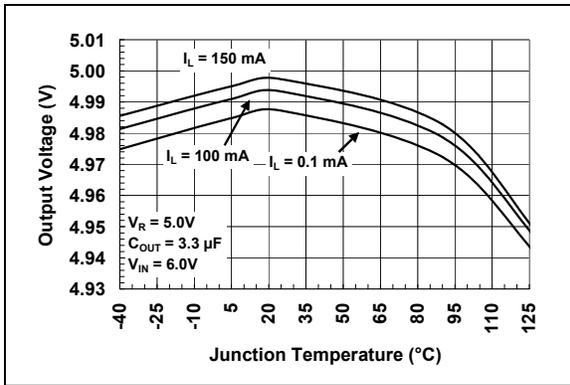
**Note:** Unless otherwise indicated,  $V_{IN} = V_R + 1V$ ,  $I_L = 100 \mu A$ ,  $C_{OUT} = 3.3 \mu F$ ,  $\overline{SHDN} > V_{IH}$ ,  $T_A = +25^\circ C$ .



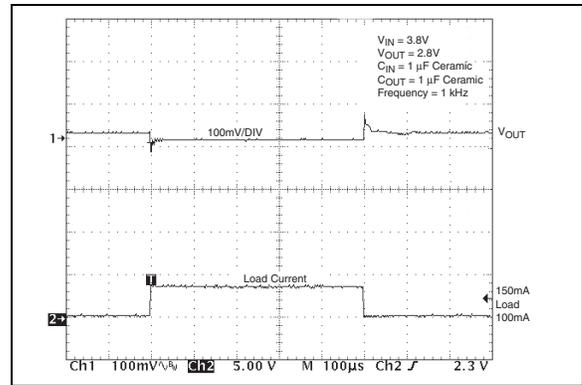
**FIGURE 2-13:** Supply Current vs. Junction Temperature.



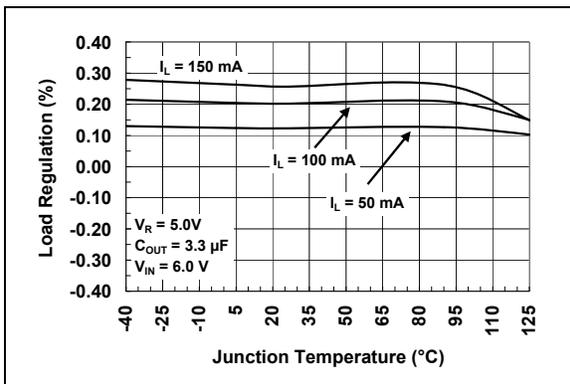
**FIGURE 2-16:** Dropout Voltage vs. Junction Temperature.



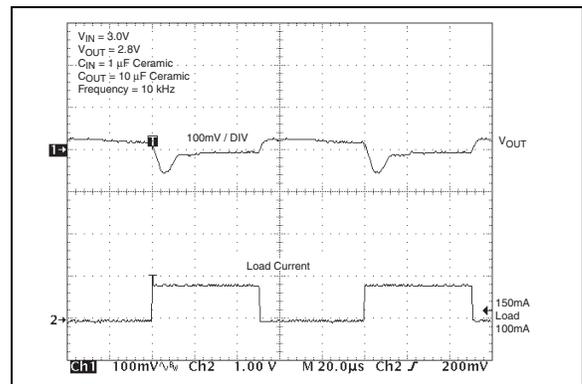
**FIGURE 2-14:** Output Voltage vs. Junction Temperature.



**FIGURE 2-17:** Load Transient Response. ( $C_{OUT} = 1 \mu F$ ).



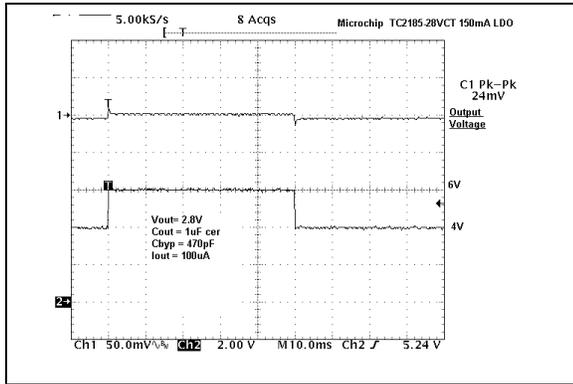
**FIGURE 2-15:** Load Regulation vs. Junction Temperature.



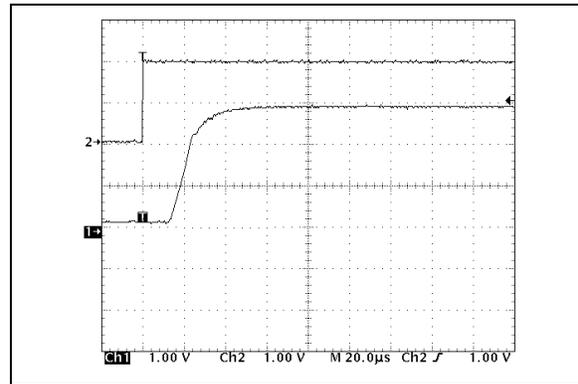
**FIGURE 2-18:** Load Transient Response. ( $C_{OUT} = 10 \mu F$ ).

# TC2014/2015/2185

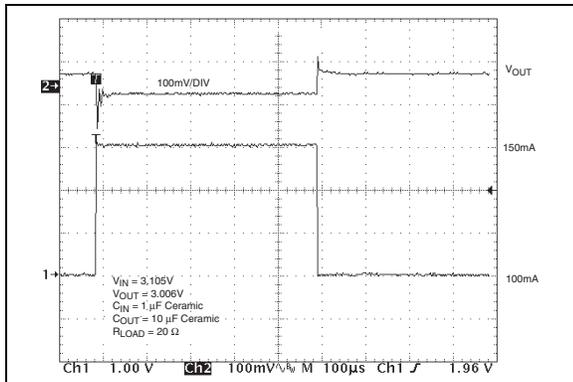
Note: Unless otherwise indicated,  $V_{IN} = V_R + 1V$ ,  $I_L = 100 \mu A$ ,  $C_{OUT} = 3.3 \mu F$ ,  $\overline{SHDN} > V_{IH}$ ,  $T_A = +25^\circ C$ .



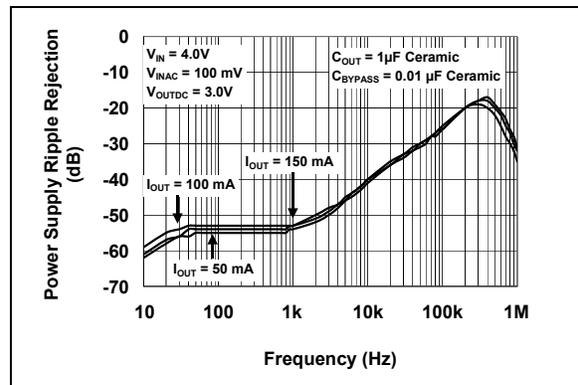
**FIGURE 2-19:** Line Transient Response. ( $C_{OUT} = 1 \mu F$ ).



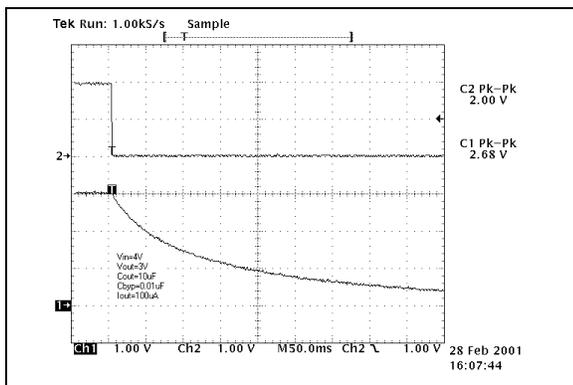
**FIGURE 2-22:** Wake-Up Response.



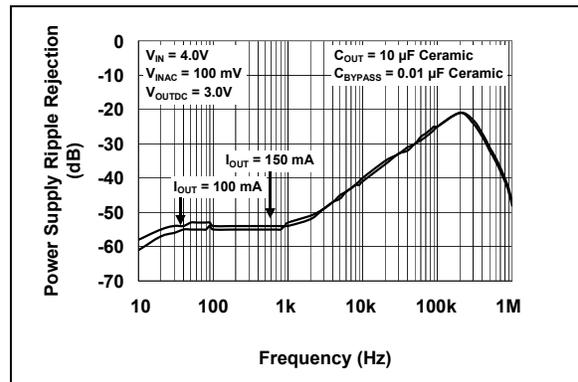
**FIGURE 2-20:** Load Transient Response in Dropout. ( $C_{OUT} = 10 \mu F$ ).



**FIGURE 2-23:** PSRR vs. Frequency ( $C_{OUT} = 1 \mu F$  Ceramic).

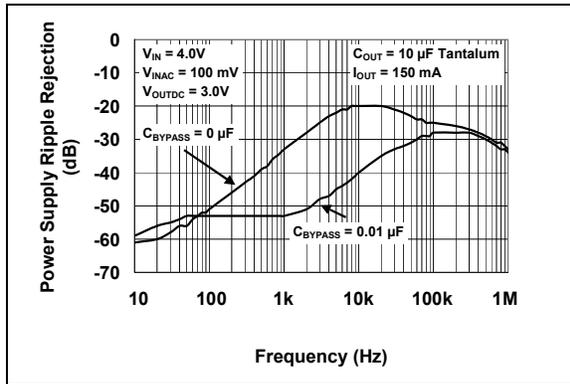


**FIGURE 2-21:** Shutdown Delay Time.

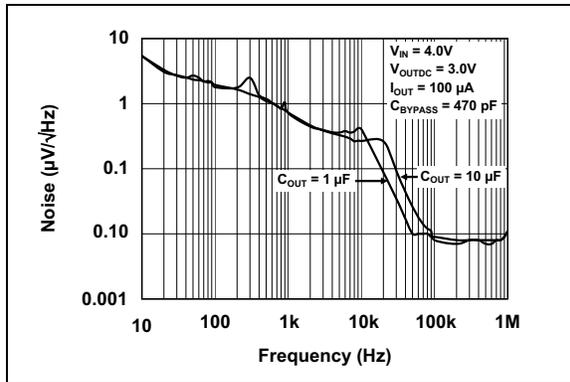


**FIGURE 2-24:** PSRR vs. Frequency ( $C_{OUT} = 10 \mu F$  Ceramic).

**Note:** Unless otherwise indicated,  $V_{IN} = V_R + 1V$ ,  $I_L = 100 \mu A$ ,  $C_{OUT} = 3.3 \mu F$ ,  $\overline{SHDN} > V_{IH}$ ,  $T_A = +25^\circ C$ .



**FIGURE 2-25:** PSRR vs. Frequency ( $C_{OUT} = 10 \mu F$  Tantalum).



**FIGURE 2-26:** Output Noise vs. Frequency.

## 3.0 PIN DESCRIPTIONS

The descriptions of the pins are described in [Table 3-1](#).

**TABLE 3-1: PIN FUNCTION TABLE**

Pin No.	Symbol	Description
1	$V_{IN}$	Unregulated supply input
2	GND	Ground terminal
3	$\overline{\text{SHDN}}$	Shutdown control input
4	Bypass	Reference bypass input
5	$V_{OUT}$	Regulated voltage output

### 3.1 Unregulated Supply Input ( $V_{IN}$ )

Connect the unregulated input supply to the  $V_{IN}$  pin. If there is a large distance between the input supply and the LDO regulator, some input capacitance is necessary for proper operation. A 1  $\mu\text{F}$  capacitor, connected from  $V_{IN}$  to ground, is recommended for most applications.

### 3.2 Ground Terminal (GND)

Connect the unregulated input supply ground return to GND. Also connect one side of the 1  $\mu\text{F}$  typical input decoupling capacitor close to this pin and one side of the output capacitor  $C_{OUT}$  to this pin.

### 3.3 Shutdown Control Input ( $\overline{\text{SHDN}}$ )

The regulator is fully enabled when a logic-high is applied to  $\overline{\text{SHDN}}$ . The regulator enters shutdown when a logic-low is applied to this input. During shutdown, the output voltage falls to zero and the supply current is reduced to 0.5  $\mu\text{A}$  (max).

### 3.4 Reference Bypass Input (Bypass)

Connecting a low-value ceramic capacitor to Bypass will further reduce output voltage noise and improve the Power Supply Ripple Rejection (PSRR) performance of the LDO. Typical values from 470 pF to 0.01  $\mu\text{F}$  are suggested. While smaller and larger values can be used, these affect the speed at which the LDO output voltage rises when input power is applied. The larger the bypass capacitor, the slower the output voltage will rise.

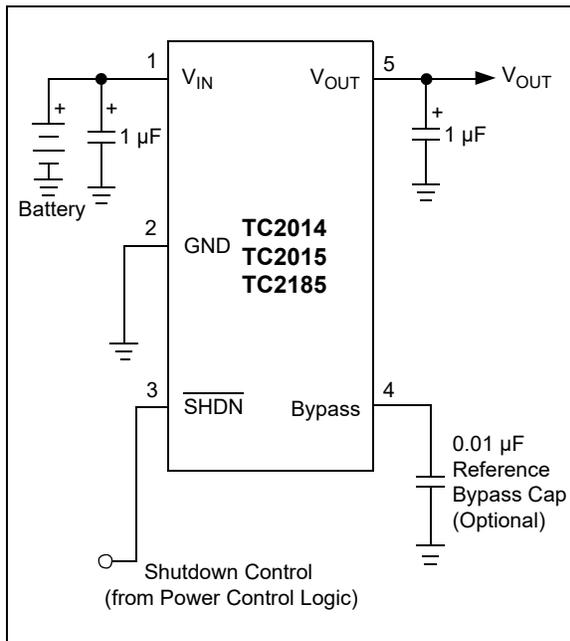
### 3.5 Regulated Voltage Output ( $V_{OUT}$ )

Connect the output load to  $V_{OUT}$  of the LDO. Also connect one side of the LDO output decoupling capacitor as close as possible to the  $V_{OUT}$  pin.

## 4.0 DETAILED DESCRIPTION

The TC2014, TC2015 and TC2185 are precision fixed-output voltage regulators (if an adjustable version is needed, see the TC1070, TC1071 and TC1187 (DS20001353) data sheet). Unlike bipolar regulators, the TC2014, TC2015 and TC2185 supply current does not increase with load current. In addition, the LDO's output voltage is stable using 1  $\mu\text{F}$  of ceramic or tantalum capacitance over the entire specified input voltage range and output current range.

Figure 4-1 shows a typical application circuit. The regulator is enabled anytime the shutdown input (SHDN) is at or above  $V_{IH}$ , and disabled (shutdown) when SHDN is at or below  $V_{IL}$ . SHDN may be controlled by a CMOS logic gate or I/O port of a microcontroller. If the SHDN input is not required, it should be connected directly to the input supply. While in shutdown, the supply current decreases to 0.05  $\mu\text{A}$  (typical) and  $V_{OUT}$  falls to zero volts.



**FIGURE 4-1:** Typical Application Circuit.

## 4.1 Bypass Input

A 0.01  $\mu\text{F}$  ceramic capacitor, connected from the Bypass input to ground, reduces noise present on the internal reference, which, in turn, significantly reduces output noise. If output noise is not a concern, this input may be left unconnected. Larger capacitor values may be used, but the result is a longer time period to rated output voltage when power is initially applied.

## 4.2 Output Capacitor

A 1  $\mu\text{F}$  (min) capacitor from  $V_{OUT}$  to ground is required. The output capacitor should have an Effective Series Resistance (ESR) of 0.01 $\Omega$  to 5 $\Omega$  for  $V_{OUT} \geq 2.5\text{V}$ , and 0.05 $\Omega$  to 5 $\Omega$  for  $V_{OUT} < 2.5\text{V}$ . Ceramic, tantalum or aluminum electrolytic capacitors can be used. When using ceramic capacitors, X5R and X7R dielectric material are recommended due to their stable tolerance over temperature. However, other dielectrics can be used as long as the minimum output capacitance is maintained.

## 4.3 Input Capacitor

A 1  $\mu\text{F}$  capacitor should be connected from  $V_{IN}$  to GND if there is more than 10 inches of wire between the regulator and this AC filter capacitor, or if a battery is used as the power source. Aluminum electrolytic or tantalum capacitors can be used (since many aluminum electrolytic capacitors freeze at approximately  $-30^{\circ}\text{C}$ , solid tantalum are recommended for applications operating below  $-25^{\circ}\text{C}$ ). When operating from sources other than batteries, supply-noise rejection and transient response can be improved by increasing the value of the input and output capacitors and employing passive filtering techniques.

## 5.0 THERMAL CONSIDERATIONS

### 5.1 Thermal Shutdown

Integrated thermal protection circuitry shuts the regulator off when the die temperature exceeds approximately 160°C. The regulator remains off until the die temperature cools to approximately 150°C.

### 5.2 Power Dissipation

The amount of power the regulator dissipates is primarily a function of input voltage, output voltage and output current.

The following equation is used to calculate worst-case power dissipation.

#### EQUATION 5-1:

$$P_D \approx (V_{INMAX} - V_{OUTMIN})I_{LMAX}$$

Where:

$P_D$	=	Worst-case actual power dissipation
$V_{INMAX}$	=	Maximum voltage on $V_{IN}$
$V_{OUTMIN}$	=	Minimum regulator output voltage
$I_{LMAX}$	=	Maximum output (load) current

The maximum allowable power dissipation ( $P_{DMAX}$ ) is a function of the maximum ambient temperature ( $T_{AMAX}$ ), the maximum allowable die temperature ( $T_{JMAX}$ ) (+125°C) and the thermal resistance from junction-to-air ( $\theta_{JA}$ ). The 5-Pin SOT-23A package has a  $\theta_{JA}$  of approximately 220°C/Watt when mounted on a typical two-layer FR4 dielectric copper-clad PC board.

#### EQUATION 5-2:

$$P_{DMAX} = \frac{T_{JMAX} - T_{AMAX}}{\theta_{JA}}$$

Where all terms are previously defined.

The  $P_D$  equation can be used in conjunction with the  $P_{DMAX}$  equation to ensure that regulator thermal operation is within limits. For example:

Given:

$$\begin{aligned} V_{INMAX} &= 3.0V + 10\% \\ V_{OUTMIN} &= 2.7V - 2.5\% \\ I_{LOADMAX} &= 40 \text{ mA} \\ T_{JMAX} &= +125^\circ\text{C} \\ T_{AMAX} &= +55^\circ\text{C} \end{aligned}$$

Find:

1. Actual power dissipation
2. Maximum allowable dissipation

Actual power dissipation:

$$\begin{aligned} P_D &= (V_{INMAX} - V_{OUTMIN})I_{LMAX} \\ &= [(3.0 \times 1.1) - (2.7 \times 0.975)]40 \times 10^{-3} \\ &= 26.7 \text{ mW} \end{aligned}$$

Maximum allowable power dissipation:

$$\begin{aligned} P_{DMAX} &= \frac{T_{JMAX} - T_{AMAX}}{\theta_{JA}} \\ &= \frac{125 - 55}{220} \\ &= 318 \text{ mW} \end{aligned}$$

In this example, the TC2014 dissipates a maximum of only 26.7 mW; far below the allowable limit of 318 mW. In a similar manner, the  $P_D$  and  $P_{DMAX}$  equations can be used to calculate maximum current and/or input voltage limits.

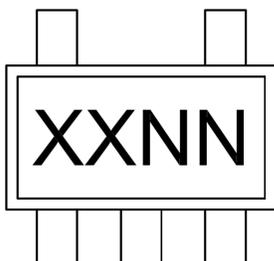
### 5.3 Layout Considerations

The primary path of heat conduction out of the package is via the package leads. Therefore, layouts having a ground plane, wide traces at the pads and wide power supply bus lines combine to lower  $\theta_{JA}$  and, therefore, increase the maximum allowable power dissipation limit.

## 6.0 PACKAGING INFORMATION

### 6.1 Package Marking Information

5-Lead SOT-23



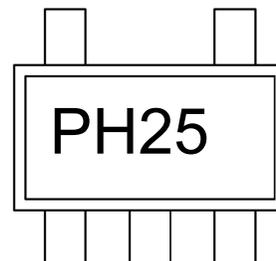
**XX** - part number code and voltage (Table 6-1)

**NN** - alphanumeric identification code

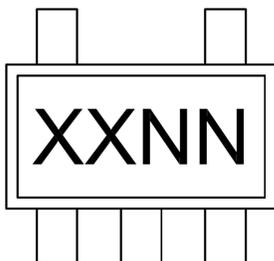
**TABLE 6-1: PART NUMBER CODE AND TEMPERATURE RANGE**

(V)	TC2014	TC2015	TC2185
1.8	PA	RA	UA
2.5	PB	RB	UB
2.6	PH	RH	UH
2.7	PC	RC	UC
2.8	PD	RD	UD
2.85	PE	RE	UE
3.0	PF	RF	UF
3.3	PG	RG	UG
5.0	PJ	RJ	UJ

Example



5-Lead SOT-23  
NiPdAu plating



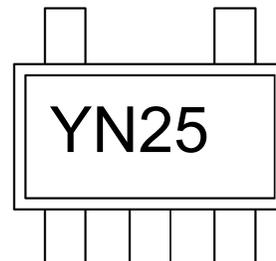
**XX** - part number code and voltage (Table 6-2)

**NN** - alphanumeric identification code

**TABLE 6-2: PART NUMBER CODE AND TEMPERATURE RANGE**

(V)	TC2014	TC2015	TC2185
2.8	Z1	—	Z2
3.3	YN	—	—

Example



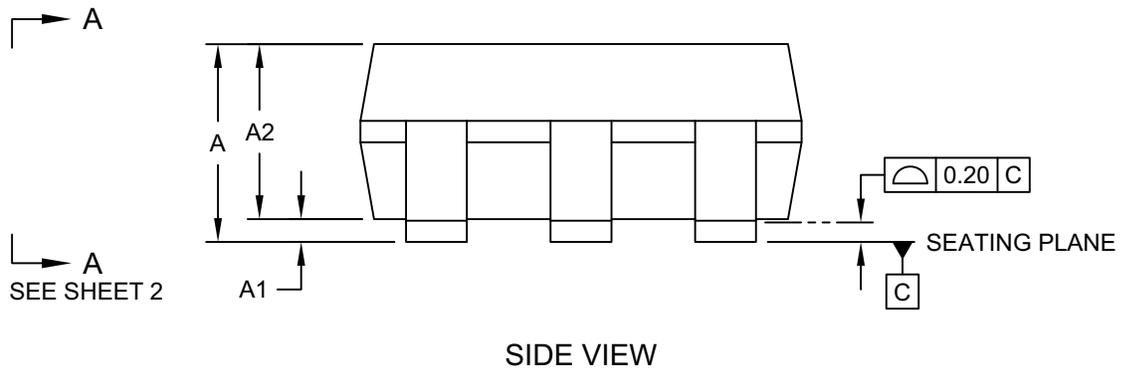
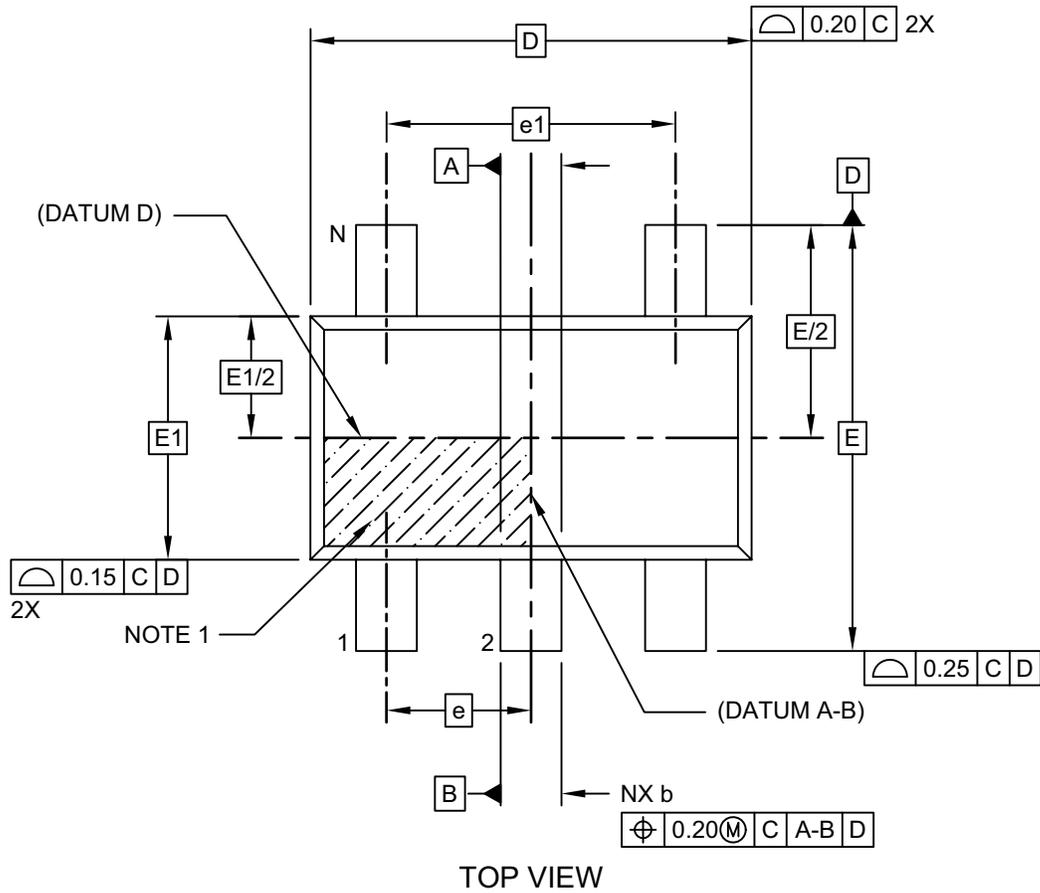
<b>Legend:</b>	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

**Note:** In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

# TC2014/2015/2185

## 5-Lead Plastic Small Outline Transistor (6BX) [SOT-23]

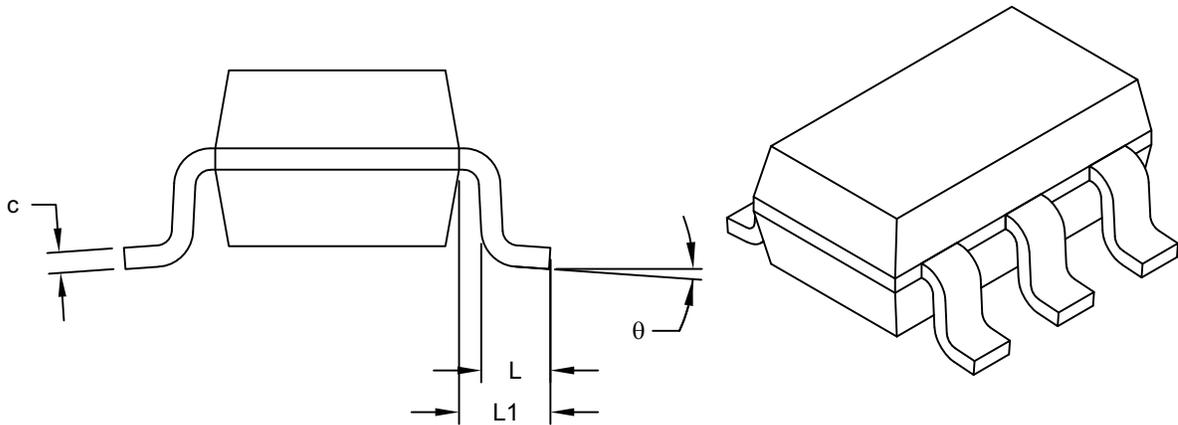
**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-091-6BX Rev H Sheet 1 of 2

## 5-Lead Plastic Small Outline Transistor (6BX) [SOT-23]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



VIEW A-A  
SHEET 1

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	5		
Pitch	e	0.95 BSC		
Outside lead pitch	e1	1.90 BSC		
Overall Height	A	0.90	-	1.45
Molded Package Thickness	A2	0.89	-	1.30
Standoff	A1	-	-	0.15
Overall Width	E	2.80 BSC		
Molded Package Width	E1	1.60 BSC		
Overall Length	D	2.90 BSC		
Foot Length	L	0.30	-	0.60
Footprint	L1	0.60 REF		
Foot Angle	θ	0°	-	10°
Lead Thickness	c	0.08	-	0.26
Lead Width	b	0.20	-	0.51

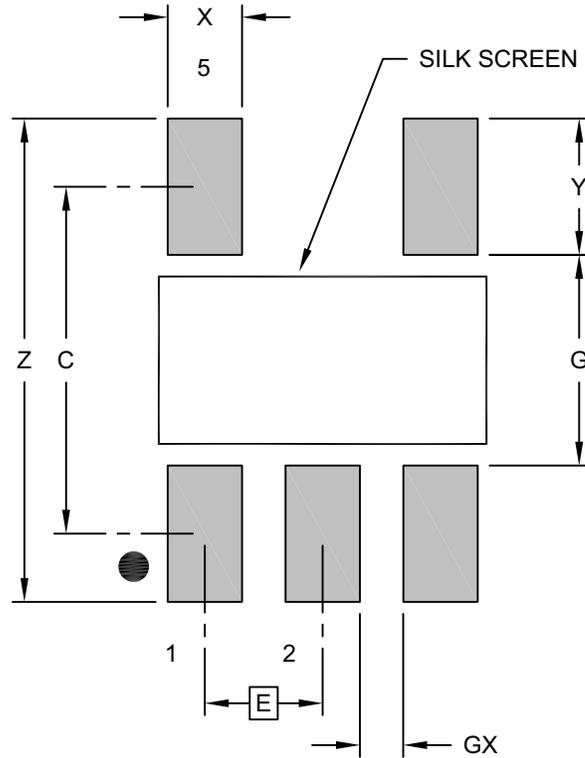
**Notes:**

- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.
- Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.  
REF: Reference Dimension, usually without tolerance, for information purposes only.

# TC2014/2015/2185

## 5-Lead Plastic Small Outline Transistor (6BX) [SOT-23]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.95 BSC		
Contact Pad Spacing	C		2.80	
Contact Pad Width (X5)	X			0.60
Contact Pad Length (X5)	Y			1.10
Distance Between Pads	G	1.70		
Distance Between Pads	GX	0.35		
Overall Width	Z			3.90

**Notes:**

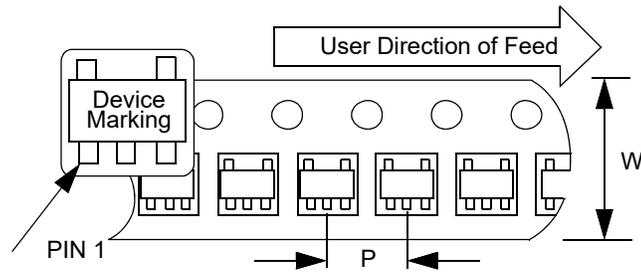
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2091-6BX Rev H

## 6.2 Taping Form

Component Taping Orientation for 5-Pin SOT-23A (EIAJ SC-74A) Devices



Standard Reel Component Orientation  
for 713 Suffix Device  
(Mark Right Side Up)

Carrier Tape, Number of Components Per Reel and Reel Size:

Package	Carrier Width (W)	Pitch (P)	Part Per Full Reel	Reel Size
5-Pin SOT-23A	8 mm	4 mm	3000	7 in.

# TC2014/2015/2185

---

---

NOTES:

## APPENDIX A: REVISION HISTORY

### Revision G (July 2023)

- Added automotive qualification to “**Features**” and added examples to “**Product Identification System**”.
- Updated “**Absolute Maximum Ratings†**” to better describe the part.
- Updated **6.0**“**Packaging Information**”.
- Minor text and format changes throughout.

### Revision F (December 2012)

- Added a note to each package outline drawing.

### Revision E (May 2006)

- Page 1: Added overtemperature to bullet for overcurrent protection in features and general description verbiage.
- Page 3: Added Thermal Shutdown die Temperature to electrical characteristics table.
- Page 3: Added Thermal Characteristics Table.
- Page 5: Added new section 5.1 and new verbiage.
- Page 13: Updated package outline drawing.

### Revision D (November 2004)

- Page 2: Changed Absolute Maximum Ratings from 6.5V to 7.0V.
- Packaging Information: Added package codes for 2.6V and 5.0V options.
- Product Identification System: Added 2.6V and 5.0V to Output voltage options.

### Revision C (December 2002)

- Numerous changes

### Revision B (May 2002)

- Numerous changes

### Revision A (May 2001)

- Original Release of this Document.

# TC2014/2015/2185

---

---

NOTES:

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>-XX</u>	<u>X</u>	<u>XXX(1)</u>	<u>XXX</u>
Device	Output Voltage	Temperature Range	Package/ Tape and Reel	Qualification
<p><b>Device:</b> TC2014: 50 mA LDO with Shutdown and V<sub>REF</sub> Bypass            TC2015: 100 mA LDO with Shutdown and V<sub>REF</sub> Bypass            TC2185: 150 mA LDO with Shutdown and V<sub>REF</sub> Bypass</p>				
<p><b>Output Voltage:</b> XX = 1.8V            XX = 2.5V            XX = 2.6V            XX = 2.7V            XX = 2.8V            XX = 2.85V            XX = 3.0V            XX = 3.3V            XX = 5.0V</p>				
<p><b>Temperature Range:</b> V = -40°C to +125°C</p>				
<p><b>Package:</b> CTTR = Plastic Small Outline Transistor (SOT-23), 5-lead, Tape and Reel            CTTRY = Plastic Small Outline Transistor (SOT-23), 5-lead, Tape and Reel, NiPdAu plating</p>				
<p><b>Qualification*:</b> Blank = Standard Part            VAO = AEQ-Q100 Automotive Qualified            *All currently available VAO variants are shown in the examples.</p>				
<p><b>Examples:</b></p> <p>a) TC2014-1.8VCTTR: 1.8V, -40°C to +125°C, 5LD SOT-23, Tape and Reel</p> <p>b) TC2014-2.85VCTTR: 2.85V, -40°C to +125°C, 5LD SOT-23, Tape and Reel</p> <p>c) TC2015-1.8VCTTR: 1.8V, -40°C to +125°C, 5LD SOT-23, Tape and Reel</p> <p>d) TC2015-2.85VCTTR: 2.85V, -40°C to +125°C, 5LD SOT-23, Tape and Reel</p> <p>e) TC2185-1.8VCTTR: 1.8V, -40°C to +125°C, 5LD SOT-23, Tape and Reel</p> <p>f) TC2185-2.8VCTTR: 2.8V, -40°C to +125°C, 5LD SOT-23, Tape and Reel</p> <p>g) TC2185-2.8VCTTRY: 2.8V, -40°C to +125°C, 5LD SOT-23, Tape and Reel</p> <p>h) TC2185-3.0VCTTR-VAO: 3.0V, -40°C to +125°C, 5LD SOT-23, Tape and Reel, AEQ-Q100 Automotive Qualified</p> <p>i) TC2185-3.3VCTTR-VAO: 3.3V, -40°C to +125°C, 5LD SOT-23, Tape and Reel, AEQ-Q100 Automotive Qualified</p>				
<p><b>Note 1:</b> Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.</p>				

# TC2014/2015/2185

---

---

NOTES:

---

---

**Note the following details of the code protection feature on Microchip products:**

- Microchip products meet the specifications contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is secure when used in the intended manner, within operating specifications, and under normal conditions.
- Microchip values and aggressively protects its intellectual property rights. Attempts to breach the code protection features of Microchip product is strictly prohibited and may violate the Digital Millennium Copyright Act.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of its code. Code protection does not mean that we are guaranteeing the product is "unbreakable" Code protection is constantly evolving. Microchip is committed to continuously improving the code protection features of our products.

---

This publication and the information herein may be used only with Microchip products, including to design, test, and integrate Microchip products with your application. Use of this information in any other manner violates these terms. Information regarding device applications is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. Contact your local Microchip sales office for additional support or, obtain additional support at <https://www.microchip.com/en-us/support/design-help/client-support-services>.

THIS INFORMATION IS PROVIDED BY MICROCHIP "AS IS". MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION INCLUDING BUT NOT LIMITED TO ANY IMPLIED WARRANTIES OF NON-INFRINGEMENT, MERCHANTABILITY, AND FITNESS FOR A PARTICULAR PURPOSE, OR WARRANTIES RELATED TO ITS CONDITION, QUALITY, OR PERFORMANCE.

IN NO EVENT WILL MICROCHIP BE LIABLE FOR ANY INDIRECT, SPECIAL, PUNITIVE, INCIDENTAL, OR CONSEQUENTIAL LOSS, DAMAGE, COST, OR EXPENSE OF ANY KIND WHATSOEVER RELATED TO THE INFORMATION OR ITS USE, HOWEVER CAUSED, EVEN IF MICROCHIP HAS BEEN ADVISED OF THE POSSIBILITY OR THE DAMAGES ARE FORESEEABLE. TO THE FULLEST EXTENT ALLOWED BY LAW, MICROCHIP'S TOTAL LIABILITY ON ALL CLAIMS IN ANY WAY RELATED TO THE INFORMATION OR ITS USE WILL NOT EXCEED THE AMOUNT OF FEES, IF ANY, THAT YOU HAVE PAID DIRECTLY TO MICROCHIP FOR THE INFORMATION.

Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights unless otherwise stated.

For information regarding Microchip's Quality Management Systems, please visit [www.microchip.com/quality](http://www.microchip.com/quality).

**Trademarks**

The Microchip name and logo, the Microchip logo, Adaptec, AVR, AVR logo, AVR Freaks, BesTime, BitCloud, CryptoMemory, CryptoRF, dsPIC, flexPWR, HELDO, IGLoo, JukeBlox, KeeLoq, Klear, LANCheck, LinkMD, maXStylus, maXTouch, MediaLB, megaAVR, Microsemi, Microsemi logo, MOST, MOST logo, MPLAB, OptoLyzer, PIC, picoPower, PICSTART, PIC32 logo, PolarFire, Prochip Designer, QTouch, SAM-BA, SenGenuity, SpyNIC, SST, SST Logo, SuperFlash, Symmetricom, SyncServer, Tachyon, TimeSource, tinyAVR, UNI/O, Vectron, and XMEGA are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

AgileSwitch, APT, ClockWorks, The Embedded Control Solutions Company, EtherSynch, Flashtec, Hyper Speed Control, HyperLight Load, Libero, motorBench, mTouch, Powermite 3, Precision Edge, ProASIC, ProASIC Plus, ProASIC Plus logo, Quiet-Wire, SmartFusion, SyncWorld, Temux, TimeCesium, TimeHub, TimePictra, TimeProvider, TrueTime, and ZL are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Adjacent Key Suppression, AKS, Analog-for-the-Digital Age, Any Capacitor, AnyIn, AnyOut, Augmented Switching, BlueSky, BodyCom, Clockstudio, CodeGuard, CryptoAuthentication, CryptoAutomotive, CryptoCompanion, CryptoController, dsPICDEM, dsPICDEM.net, Dynamic Average Matching, DAM, ECAN, Espresso T1S, EtherGREEN, GridTime, IdealBridge, In-Circuit Serial Programming, ICSP, INICnet, Intelligent Paralleling, IntelliMOS, Inter-Chip Connectivity, JitterBlocker, Knob-on-Display, KoD, maxCrypto, maxView, memBrain, Mindi, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, MultiTRAK, NetDetach, Omniscient Code Generation, PICDEM, PICDEM.net, PICkit, PICtail, PowerSmart, PureSilicon, QMatrix, REAL ICE, Ripple Blocker, RTAX, RTG4, SAM-ICE, Serial Quad I/O, simpleMAP, SimpliPHY, SmartBuffer, SmartHLS, SMART-I.S., storClad, SQI, SuperSwitcher, SuperSwitcher II, Switchtec, SynchroPHY, Total Endurance, Trusted Time, TSHARC, USBCheck, VariSense, VectorBlox, VeriPHY, ViewSpan, WiperLock, XpressConnect, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

The Adaptec logo, Frequency on Demand, Silicon Storage Technology, and Symmcom are registered trademarks of Microchip Technology Inc. in other countries.

GestIC is a registered trademark of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2001-2023, Microchip Technology Incorporated and its subsidiaries.

All Rights Reserved.

ISBN: 978-1-6683-2801-9



# MICROCHIP

## Worldwide Sales and Service

### AMERICAS

**Corporate Office**  
2355 West Chandler Blvd.  
Chandler, AZ 85224-6199  
Tel: 480-792-7200  
Fax: 480-792-7277  
Technical Support:  
<http://www.microchip.com/support>  
Web Address:  
[www.microchip.com](http://www.microchip.com)

#### Atlanta

Duluth, GA  
Tel: 678-957-9614  
Fax: 678-957-1455

#### Austin, TX

Tel: 512-257-3370

#### Boston

Westborough, MA  
Tel: 774-760-0087  
Fax: 774-760-0088

#### Chicago

Itasca, IL  
Tel: 630-285-0071  
Fax: 630-285-0075

#### Dallas

Addison, TX  
Tel: 972-818-7423  
Fax: 972-818-2924

#### Detroit

Novi, MI  
Tel: 248-848-4000

#### Houston, TX

Tel: 281-894-5983

#### Indianapolis

Noblesville, IN  
Tel: 317-773-8323  
Fax: 317-773-5453  
Tel: 317-536-2380

#### Los Angeles

Mission Viejo, CA  
Tel: 949-462-9523  
Fax: 949-462-9608  
Tel: 951-273-7800

#### Raleigh, NC

Tel: 919-844-7510

#### New York, NY

Tel: 631-435-6000

#### San Jose, CA

Tel: 408-735-9110  
Tel: 408-436-4270

#### Canada - Toronto

Tel: 905-695-1980  
Fax: 905-695-2078

### ASIA/PACIFIC

**Australia - Sydney**  
Tel: 61-2-9868-6733

**China - Beijing**  
Tel: 86-10-8569-7000

**China - Chengdu**  
Tel: 86-28-8665-5511

**China - Chongqing**  
Tel: 86-23-8980-9588

**China - Dongguan**  
Tel: 86-769-8702-9880

**China - Guangzhou**  
Tel: 86-20-8755-8029

**China - Hangzhou**  
Tel: 86-571-8792-8115

**China - Hong Kong SAR**  
Tel: 852-2943-5100

**China - Nanjing**  
Tel: 86-25-8473-2460

**China - Qingdao**  
Tel: 86-532-8502-7355

**China - Shanghai**  
Tel: 86-21-3326-8000

**China - Shenyang**  
Tel: 86-24-2334-2829

**China - Shenzhen**  
Tel: 86-755-8864-2200

**China - Suzhou**  
Tel: 86-186-6233-1526

**China - Wuhan**  
Tel: 86-27-5980-5300

**China - Xian**  
Tel: 86-29-8833-7252

**China - Xiamen**  
Tel: 86-592-2388138

**China - Zhuhai**  
Tel: 86-756-3210040

### ASIA/PACIFIC

**India - Bangalore**  
Tel: 91-80-3090-4444

**India - New Delhi**  
Tel: 91-11-4160-8631

**India - Pune**  
Tel: 91-20-4121-0141

**Japan - Osaka**  
Tel: 81-6-6152-7160

**Japan - Tokyo**  
Tel: 81-3-6880-3770

**Korea - Daegu**  
Tel: 82-53-744-4301

**Korea - Seoul**  
Tel: 82-2-554-7200

**Malaysia - Kuala Lumpur**  
Tel: 60-3-7651-7906

**Malaysia - Penang**  
Tel: 60-4-227-8870

**Philippines - Manila**  
Tel: 63-2-634-9065

**Singapore**  
Tel: 65-6334-8870

**Taiwan - Hsin Chu**  
Tel: 886-3-577-8366

**Taiwan - Kaohsiung**  
Tel: 886-7-213-7830

**Taiwan - Taipei**  
Tel: 886-2-2508-8600

**Thailand - Bangkok**  
Tel: 66-2-694-1351

**Vietnam - Ho Chi Minh**  
Tel: 84-28-5448-2100

### EUROPE

**Austria - Wels**  
Tel: 43-7242-2244-39  
Fax: 43-7242-2244-393

**Denmark - Copenhagen**  
Tel: 45-4485-5910  
Fax: 45-4485-2829

**Finland - Espoo**  
Tel: 358-9-4520-820

**France - Paris**  
Tel: 33-1-69-53-63-20  
Fax: 33-1-69-30-90-79

**Germany - Garching**  
Tel: 49-8931-9700

**Germany - Haan**  
Tel: 49-2129-3766400

**Germany - Heilbronn**  
Tel: 49-7131-72400

**Germany - Karlsruhe**  
Tel: 49-721-625370

**Germany - Munich**  
Tel: 49-89-627-144-0  
Fax: 49-89-627-144-44

**Germany - Rosenheim**  
Tel: 49-8031-354-560

**Israel - Ra'anana**  
Tel: 972-9-744-7705

**Italy - Milan**  
Tel: 39-0331-742611  
Fax: 39-0331-466781

**Italy - Padova**  
Tel: 39-049-7625286

**Netherlands - Drunen**  
Tel: 31-416-690399  
Fax: 31-416-690340

**Norway - Trondheim**  
Tel: 47-7288-4388

**Poland - Warsaw**  
Tel: 48-22-3325737

**Romania - Bucharest**  
Tel: 40-21-407-87-50

**Spain - Madrid**  
Tel: 34-91-708-08-90  
Fax: 34-91-708-08-91

**Sweden - Gothenberg**  
Tel: 46-31-704-60-40

**Sweden - Stockholm**  
Tel: 46-8-5090-4654

**UK - Wokingham**  
Tel: 44-118-921-5800  
Fax: 44-118-921-5820